



MPW Shuttle Service 2012

Schedule

Process	Data and Order to	Tape In	Samples Out ⁶⁾
0.18 µm HV-CMOS 20V / 50V ⁸⁾			
H18	austria <i>micro</i> systems	10-Apr-12	15-Jun-12
H18	austria <i>micro</i> systems	06-Aug-12	12-Oct-12
H18	austria <i>micro</i> systems	08-Oct-12	14-Dec-12
H18	austria <i>micro</i> systems	03-Dec-12	10-Feb-13
0.18 µm CMOS 1.8V / 2.5V / 3.3V (5V ⁷⁾)			
C18	austria <i>micro</i> systems	16-Apr-12	22-Jun-12
C18	austria <i>micro</i> systems	13-Aug-12	19-Oct-12
C18	austria <i>micro</i> systems	08-Oct-12	14-Dec-12
C18	austria <i>micro</i> systems	03-Dec-12	10-Feb-13
0.35 µm HV-CMOS 20V / 50V / 120V (embedded Flash ⁵⁾)			
H35B4D3	austria <i>micro</i> systems	20-Feb-12	20-Apr-12
H35B4D3	austria <i>micro</i> systems	02-May-12	29-Jun-12
H35B4D3	austria <i>micro</i> systems	20-Aug-12	19-Oct-12
H35B4D3	austria <i>micro</i> systems	12-Nov-12	11-Jan-13
0.35 µm CMOS 3.3V / 5V (embedded Flash ⁵⁾) and 0.35 µm Opto-CMOS ²⁾			
C35 ¹⁾	austria <i>micro</i> systems	13-Feb-12	30-Mar-12
C35 ^{1) 2)}	Fraunhofer IIS	21-Mar-12	11-May-12
C35 ¹⁾	austria <i>micro</i> systems	29-May-12	13-Jul-12
C35 ¹⁾	Fraunhofer IIS	16-Jul-12	07-Sep-12
C35 ¹⁾	austria <i>micro</i> systems	03-Sep-12	19-Oct-12
C35 ^{1) 2)}	Fraunhofer IIS	29-Oct-12	12-Dec-12
C35 ¹⁾	austria <i>micro</i> systems	10-Dec-12	25-Jan-13
0.35 µm SiGe-BiCMOS 3.3V / 5V 2P/4M			
S35	austria <i>micro</i> systems	05-Mar-12	04-May-12
S35	austria <i>micro</i> systems	11-Jun-12	10-Aug-12
S35	austria <i>micro</i> systems	10-Sep-12	09-Nov-12
S35	austria <i>micro</i> systems	26-Nov-12	25-Jan-13
Additional MPW Shuttles are scheduled by our partners			
Fraunhofer IIS www.iis.fraunhofer.de		 Europractice www.europractice-ic.com	
CMP cmp.imag.fr		 MOSIS www.mosis.com	
DNP www.dnp.co.jp		 TOPPAN www.toptdc.com	
CONTACTS:			
austria <i>micro</i> systems mailto:sigurd.hellinger@austriamicrosystems.com		Fraunhofer IIS mailto:virtual-asic@iis.fraunhofer.de	

Price List

Issue November 2011

Process Family	Unit Price in EURO / mm ²	Minimum Charge in EURO	Comment
0.35 µm CMOS	810 ⁴⁾	9.850 ⁴⁾	
0.35 µm Opto-CMOS	1.010 ⁴⁾	14.500 ⁴⁾	
0.35 µm SiGe-BiCMOS	1.220 ⁴⁾	9.850 ⁴⁾	
0.35 µm HV-CMOS	1.140 ⁴⁾	9.850 ⁴⁾	
0.18 µm HV-CMOS	1.480 ⁴⁾	22.900 ⁴⁾	
0.18 µm CMOS	1.290 ⁴⁾	18.900 ⁴⁾	
0.35 µm CMOS embedded Flash ⁵⁾	price on request	price on request	
0.35 µm HV-CMOS embedded Flash ⁵⁾	price on request	price on request	

Standard Services

The participation on the austria *micro* systems MPW service includes the delivery of 40 dice.

Option: Double placement of a chip on the MPW cluster duplicates unit prices, minimum charges and maximum number of available dice or assembled parts, respectively.

Note: Process stops, wafer probe tests or wafer shipments are not possible for MPWs.

Additional Services

Additional Services	Unit Price in EURO	Comment
Additional Dice	Quotation required!	Up to 100 possible from single placement on MPW.
10 parts in ceramic package with taped lid	1.000 per lot	Min. 1 lot
10 parts in scoop&goop package ³⁾	1.000 per lot	Min. 1 lot
50 parts in plastic package up to 84 pins	2.500 per lot	Max. 2 lots (100 pcs). Larger qty. through multiple placement on MPW.

Notes

¹⁾ Represents different process options (exception: RF-CMOS, e.g. C35B4M3), designs with 3 metal layers will be processed as separate lot split.

²⁾ Opto option available on request. Opto CMOS process only available for 2 poly / 4 metal.

³⁾ Availability check necessary at tape in.

⁴⁾ This price list is only valid for MPW starts at austria *micro* systems.

⁵⁾ EEPROM option available on request, quotation required. Licence fee for Flash block not included.

⁶⁾ The Sample Out dates are without obligation. The total cycle time includes MPW cluster preparation, wafer back-lapping, dicing, assembling in ceramic or the scoop&goop package. For plastic assembly an additional cycle time of 3 weeks has to be calculated.

⁷⁾ Available process options C18

Important note: In addition to the Foundry Service Request Form, the 0.18 µm Addendum Document must be submitted at tape out!

⁸⁾ Available process options H18

Important note: In addition to the Foundry Service Request Form, the 0.18 µm Addendum Document must be submitted at tape out!

Disclaimer

No implied offer: The usage of austriamicrosystems design kits and/or libraries or the participation on Multi Project Wafer runs shall not be regarded as an implied offer by austriamicrosystems to subsequently manufacture such integrated circuit. In any case each integrated circuit, which is planned for production, requires an official quotation by austriamicrosystems.

Technical Information

Technical web: asic.austriamicrosystems.com
 Tape-out form: [Foundry Request Form & 0.18 µm Addendum](#)

For orders in US \$ exchange rate to be quoted.

WE RESERVE THE RIGHTS TO MAKE CHANGES WITHOUT NOTICE!

Delivery dates are subject to change without notice.

Purchase orders are based on austria *micro* systems General Terms of Trade.